

# Dynamic Voltage Allocation Based on Mutual Information For NAND Flash Memory

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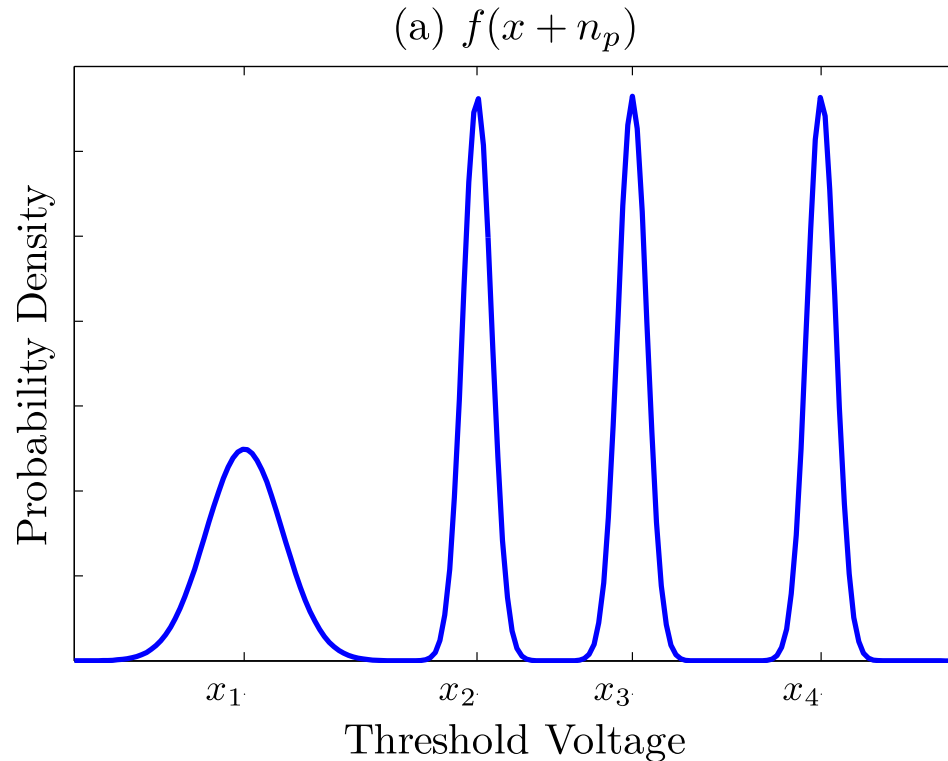
# Outline

- A three-component noise model
- Learning the channel from enhanced precision
- Dynamic voltage allocation approach

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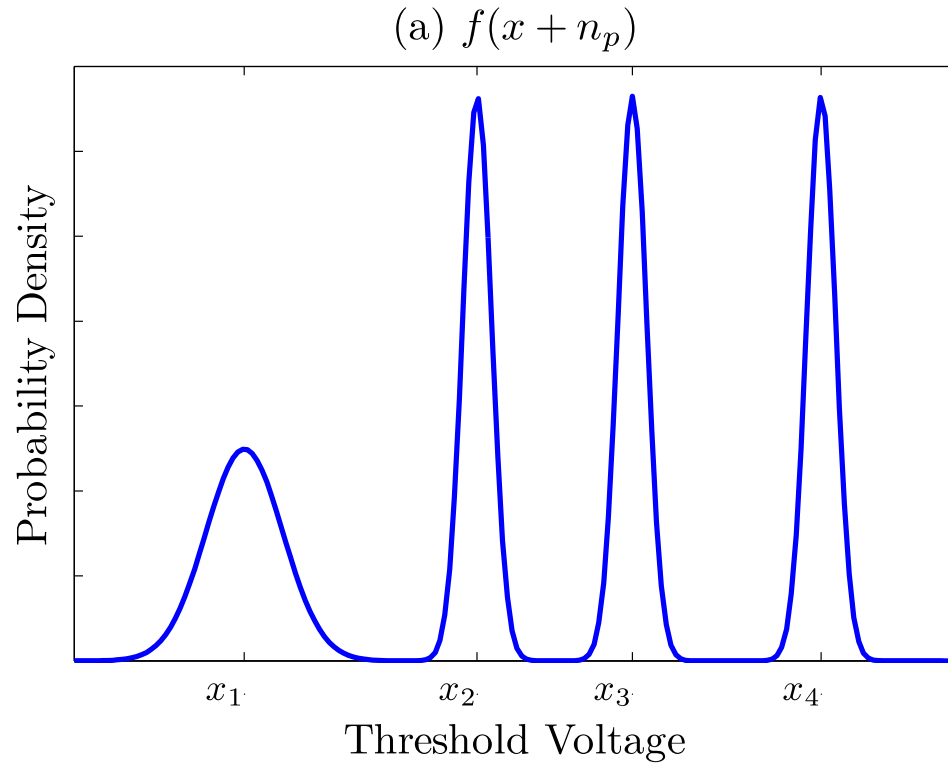
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# Programming Noise



- **Programming noise:** The baseline noise seen when writing to a new, unused cell and read it back immediately.

# Programming Noise Model



$$f_{N_p}(n_p) \sim \begin{cases} \mathcal{N}(0, \sigma_p^2) & \text{if } x > 0 \\ \mathcal{N}(0, \sigma_e^2) & \text{if } x = 0 \end{cases} \quad \text{where } S_e^2 > S_p^2$$

# Programming Noise Model

- [Compagnoni et al. 2008]

“Ultimate Accuracy for the NAND Flash Program Algorithm due to the Electron Injection Statistics”, IEEE Trans. Electron Devices, Oct. 2008.

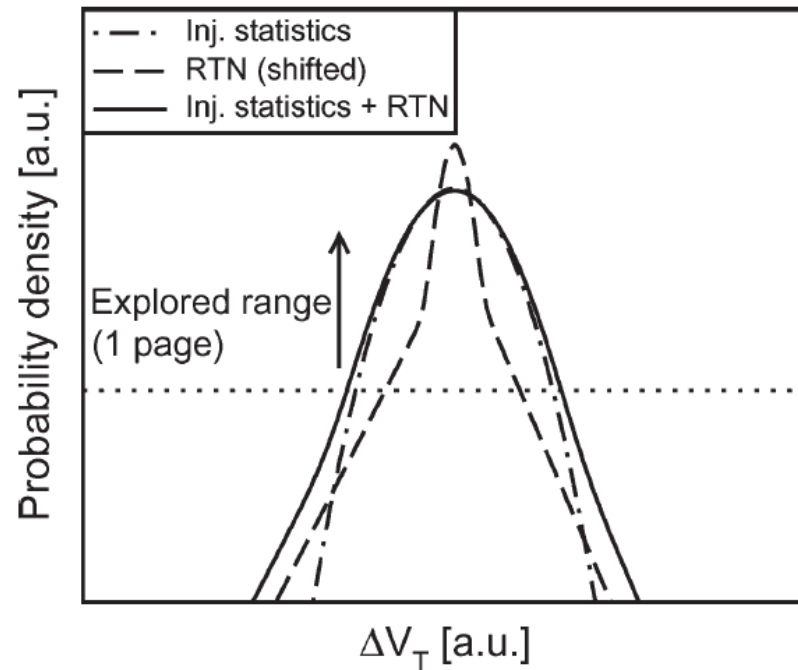
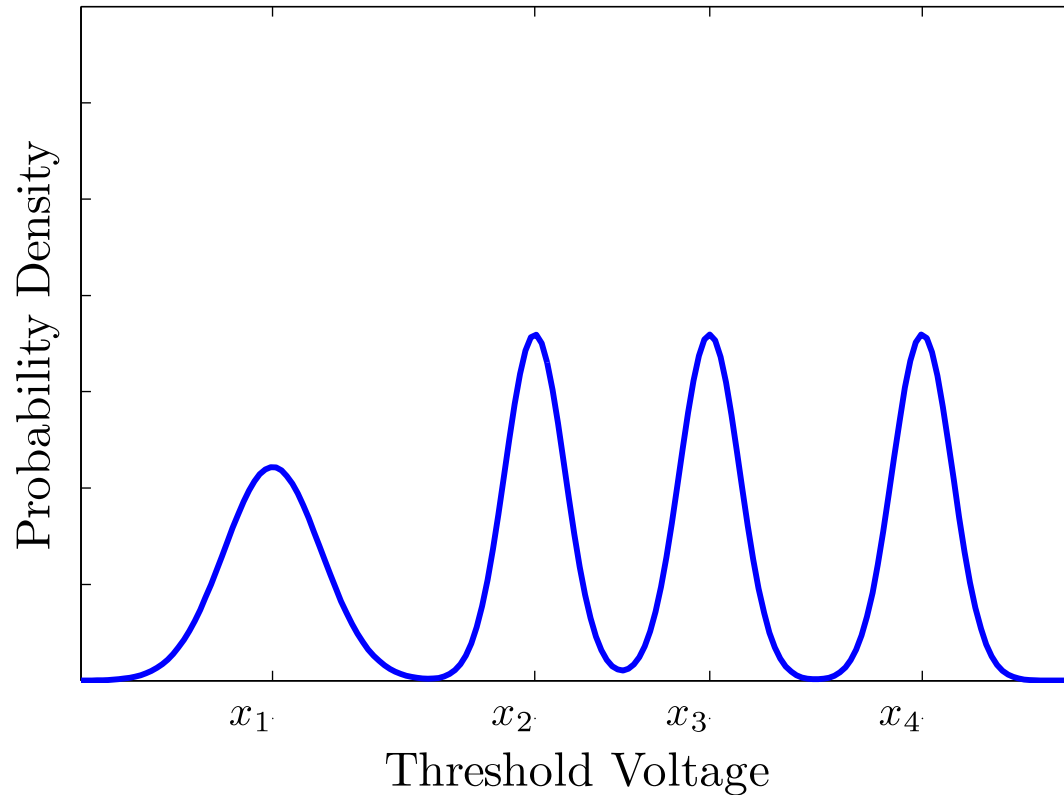


Fig. 5. Probability distribution of  $\Delta V_{T,rtn}$ , of  $\Delta V_T$  in presence of the injection statistics and including both the RTN instability and the injection spread. The  $\Delta V_{T,rtn}$  distribution has been shifted to the same average value of the  $\Delta V_T$  distribution.

# Wear-out Noise

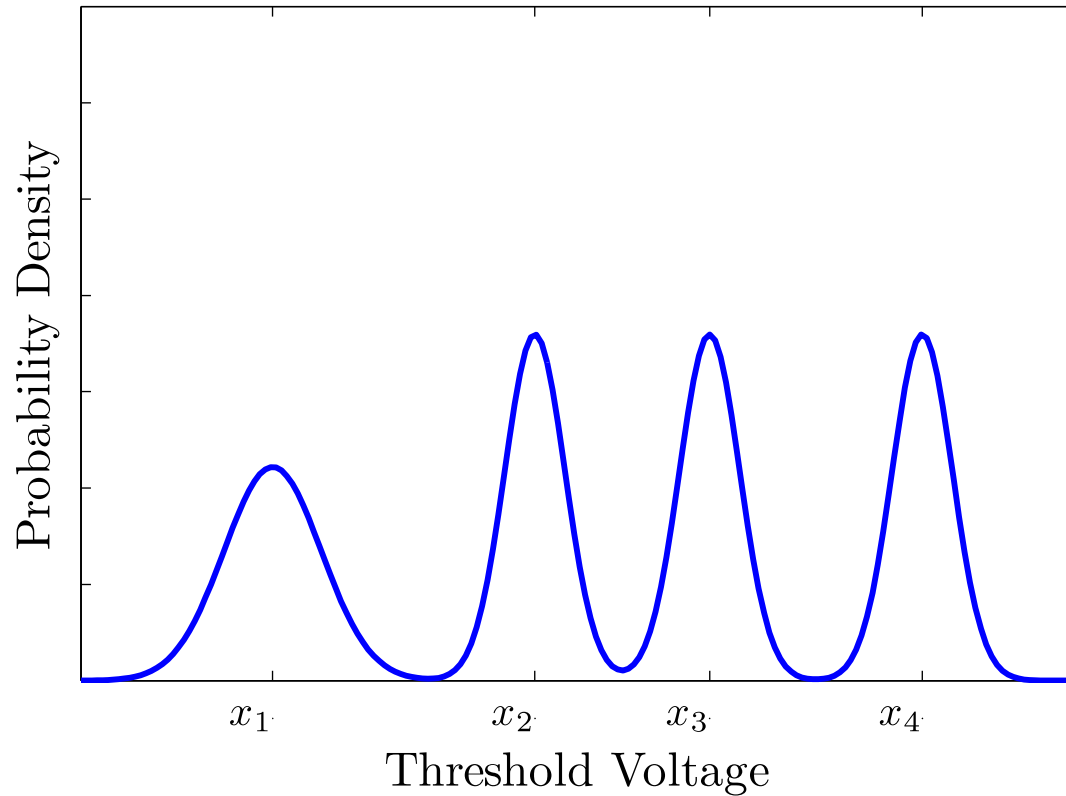
(b)  $f(x + n_p + n_w)$



- **Wear-out noise:** Additional noise seen when reading back immediately, which becomes worse as the cell has more charge programmed and erased.

# Wear-out Noise Model

(b)  $f(x + n_p + n_w)$



$$f_{N_w}(n_w) = \frac{1}{2l} e^{-\frac{|n_w|}{l}} \quad l = C_w + A_w \left( \frac{V_{\text{acc}}}{V_{\text{max}}} \right)^{0.62}$$



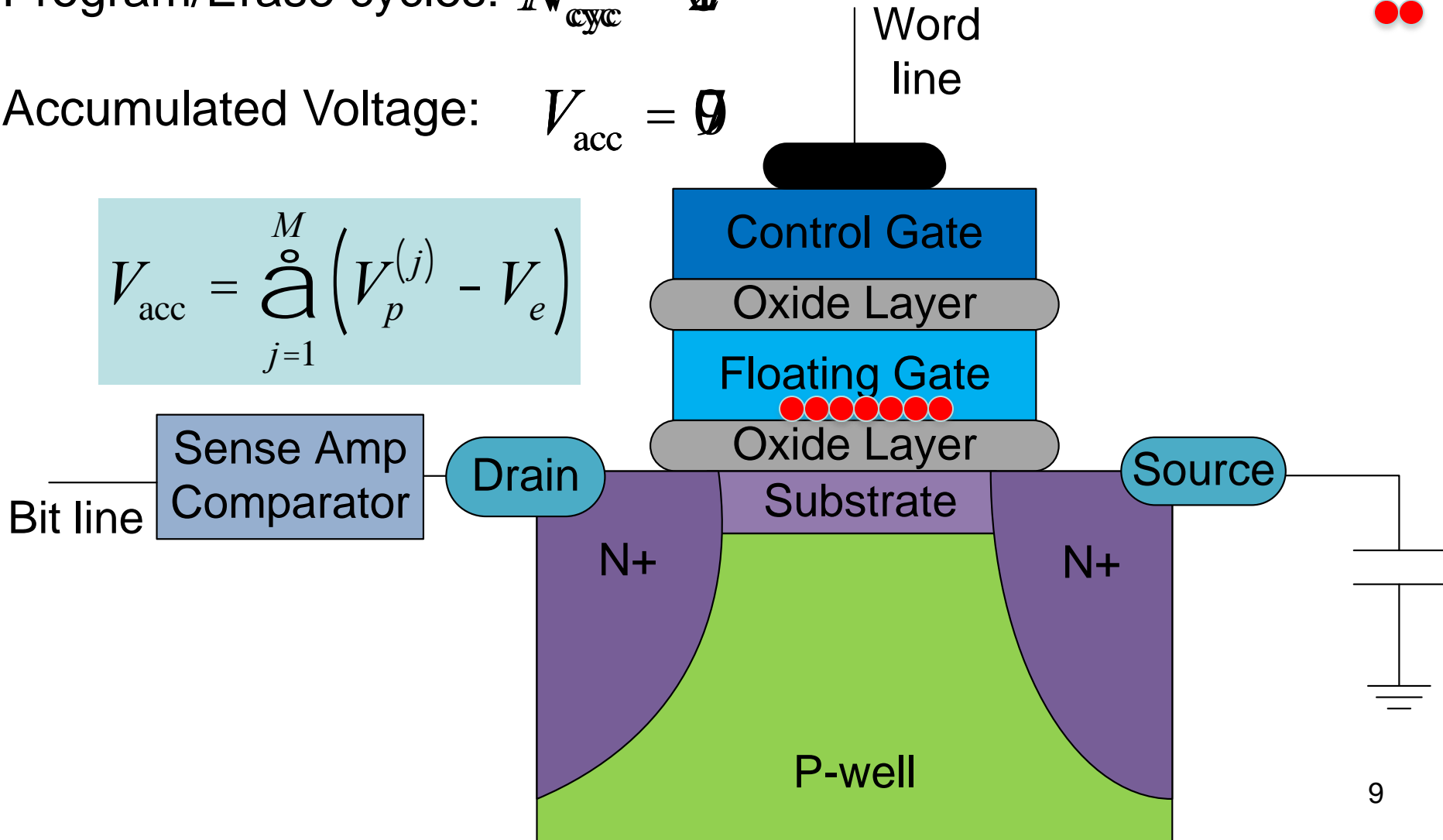
# P/E cycles vs. Accumulated Voltage

Program/Erase cycles:  $N_{\text{cyc}} = 0$

Accumulated Voltage:  $V_{\text{acc}} = 0$



$$V_{\text{acc}} = \sum_{j=1}^M (V_p^{(j)} - V_e)$$



# Wear-out Noise Model

- [Fukuda et al. 2007]

“Random telegraph noise in flash memories – model and technology scaling”, 2007  
 IEEE Int’l Electron Devices Meeting.

$$f(\Delta V_{t_{trap}}) = \frac{1}{\sigma} \cdot \exp\left(-\frac{\Delta V_{t_{trap}}}{\sigma}\right) \quad (2)$$

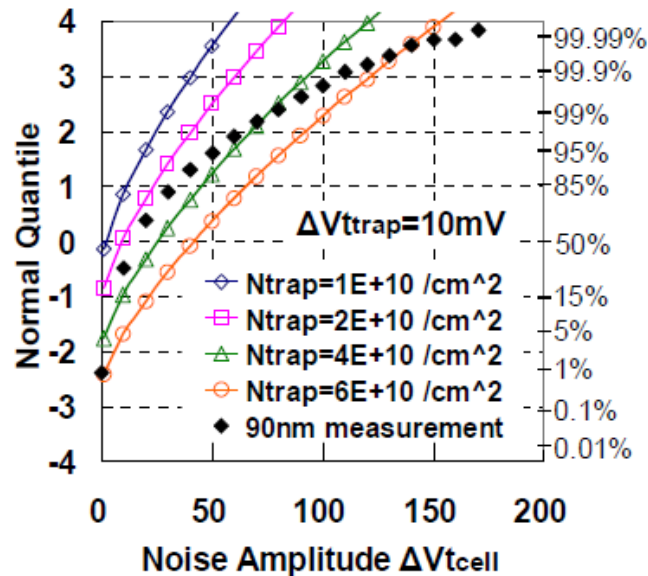
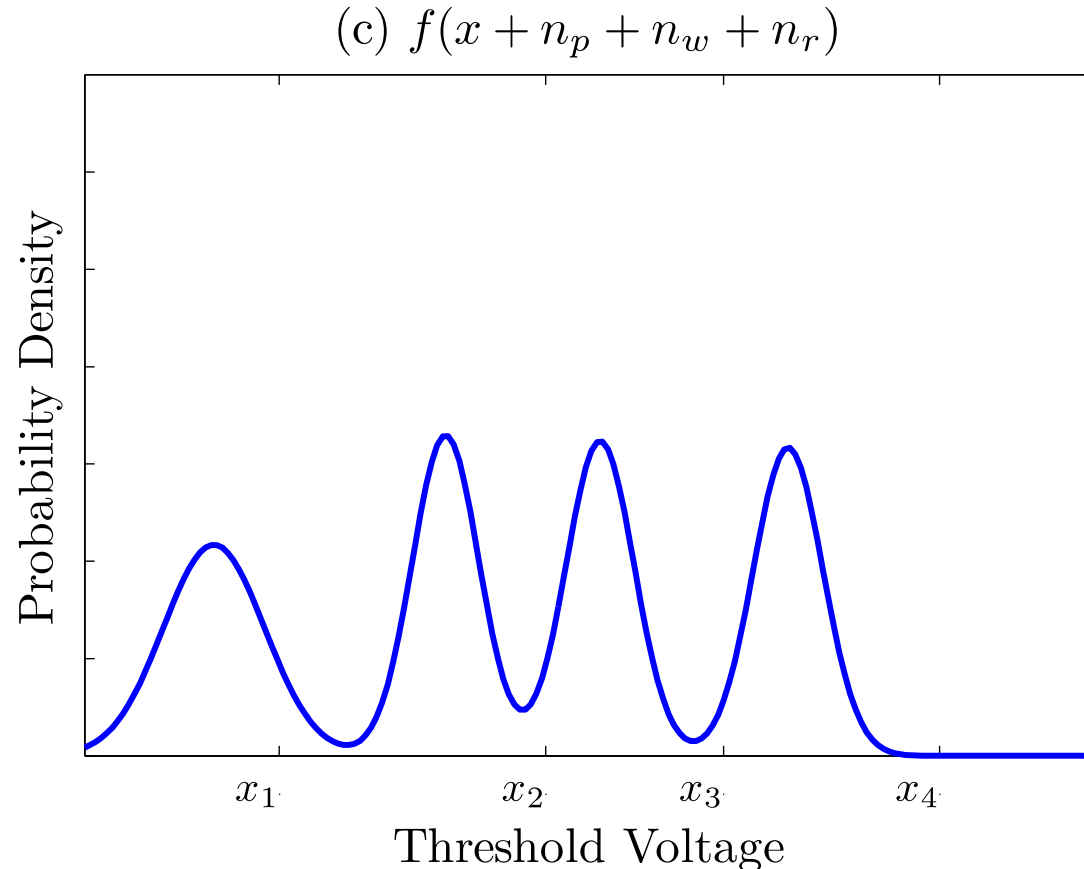


Fig. 2: Measured noise-amplitude distribution of a 90nm NAND flash memory technology. Also shown are noise distributions calculated for various interface trap densities assuming each trap contributes 10mV, Eq.(1).

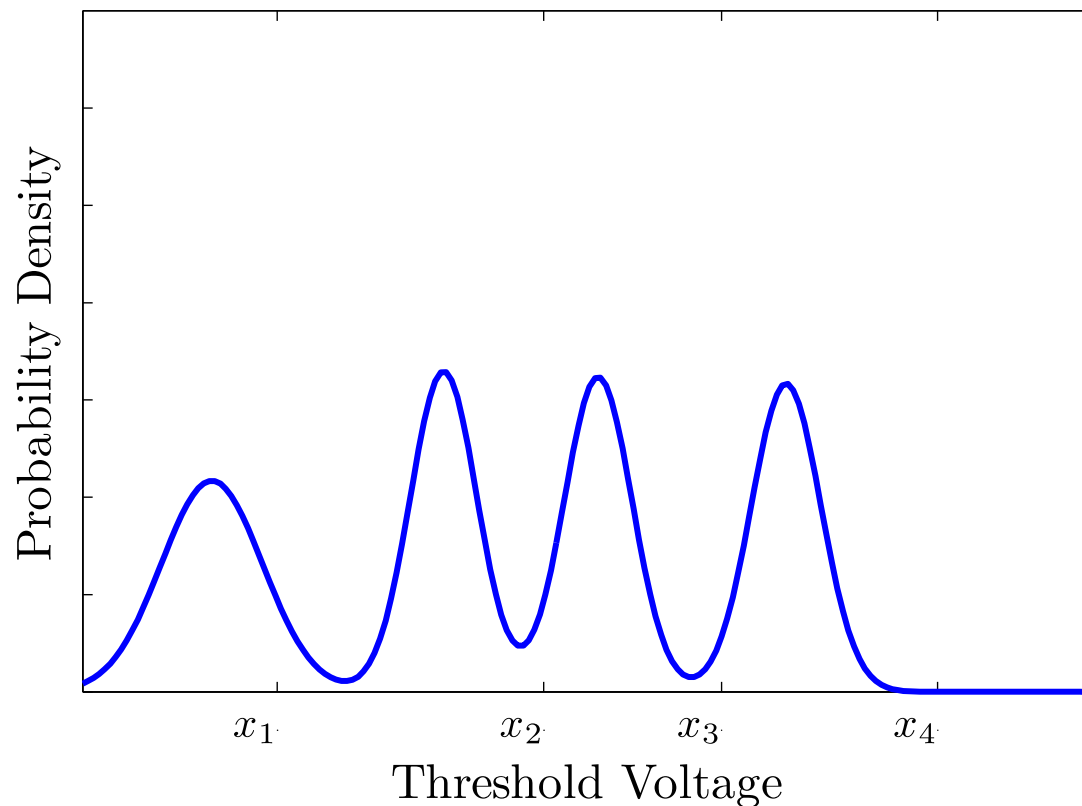
# Retention Noise



- **Retention noise:** the degradation of the threshold voltage integrity due to charge leakage after it is written.

# Retention Noise

(c)  $f(x + n_p + n_w + n_r)$



$$f_{N_r}(n_r) \sim \mathcal{N}(\mu_r, \sigma_r^2)$$

# Retention Noise Model

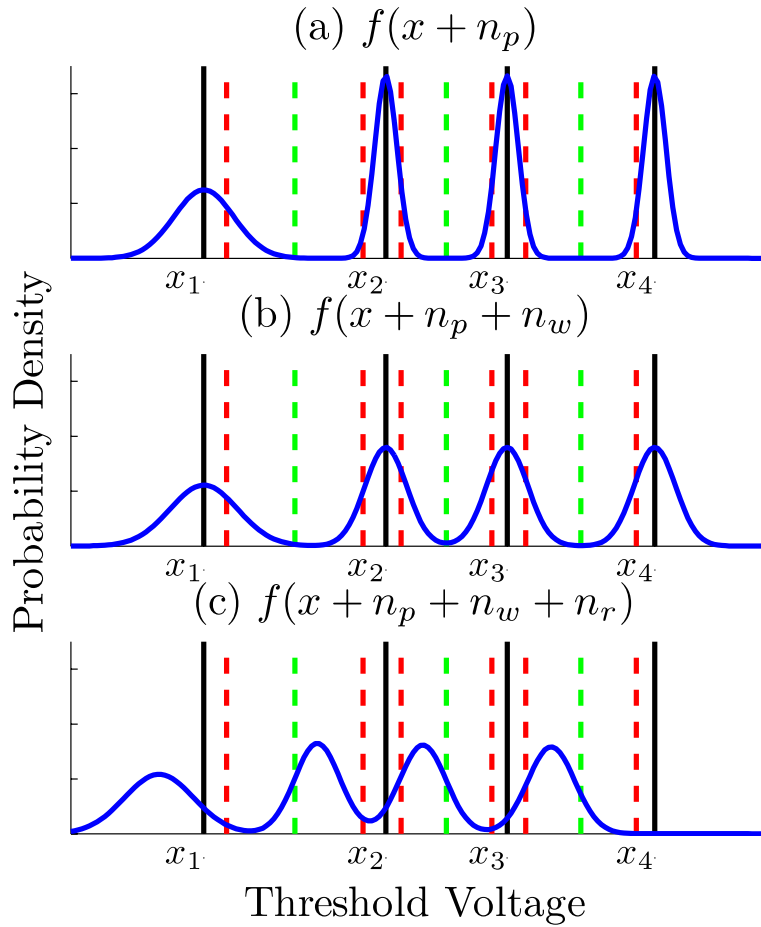
$$m_r(x, t, V_{\text{acc}}) = -x \ln\left(1 + \frac{t}{t_0}\right) \left[ A_r \left( \frac{V_{\text{acc}}}{V_{\text{max}}} \right)^{0.62} + B_r \left( \frac{V_{\text{acc}}}{V_{\text{max}}} \right)^{0.3} \right]$$

$$S_r^2(x, t, V_{\text{acc}}) = (0.1) x \ln\left(1 + \frac{t}{t_0}\right) \left[ A_r \left( \frac{V_{\text{acc}}}{V_{\text{max}}} \right)^{0.62} + B_r \left( \frac{V_{\text{acc}}}{V_{\text{max}}} \right)^{0.3} \right]^2$$

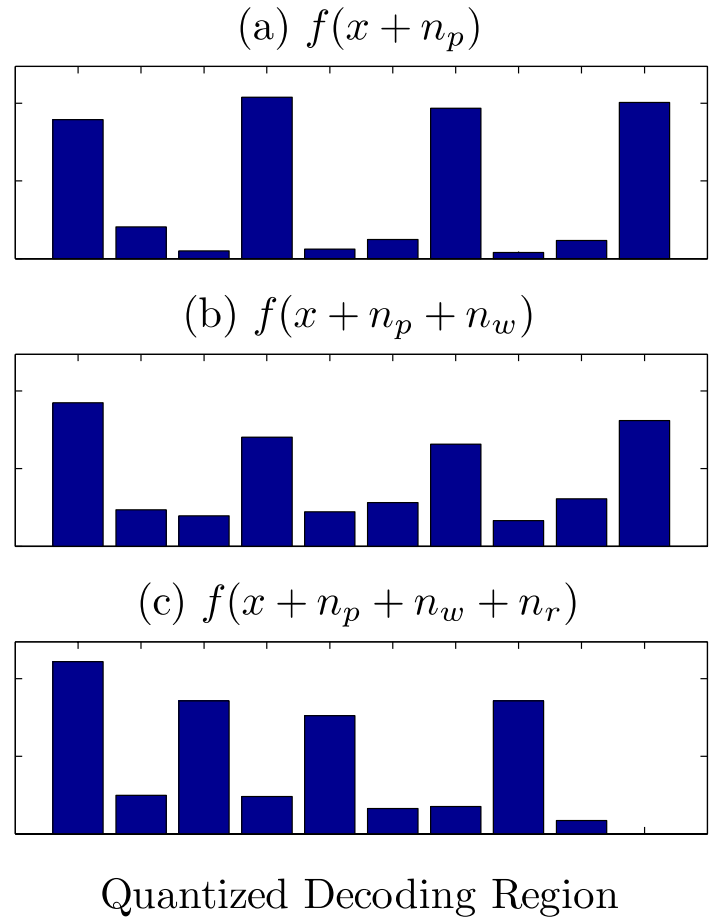
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# (Limited) Enhanced Precision Reveals Channel



Number of Cells Quantized to Each Region



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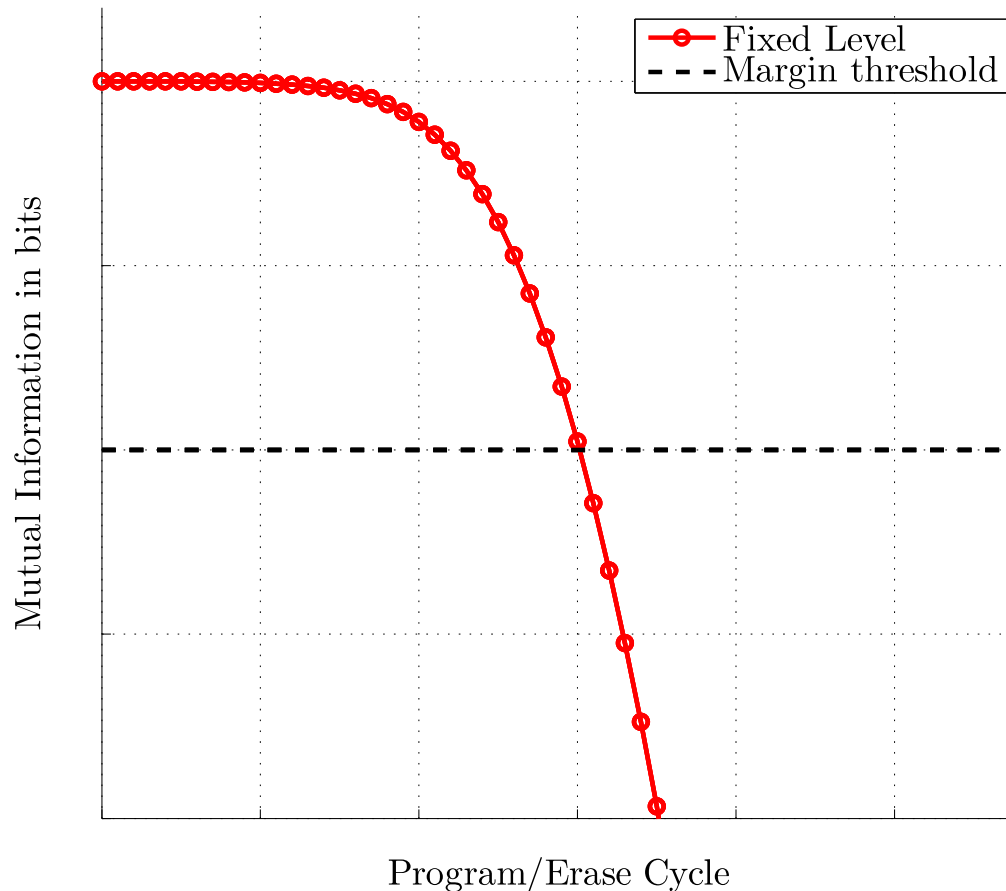
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# Computation of Capacity

$$f_{Y|X}(y|x) = \frac{e^{\sigma^2/2\lambda^2}}{2\lambda} \left[ \exp\left(\frac{y-\mu}{\lambda}\right) Q\left(\frac{y-\mu}{\sigma} + \frac{\sigma}{\lambda}\right) + \exp\left(\frac{-y+\mu}{\lambda}\right) Q\left(\frac{-y+\mu}{\sigma} + \frac{\sigma}{\lambda}\right) \right]$$

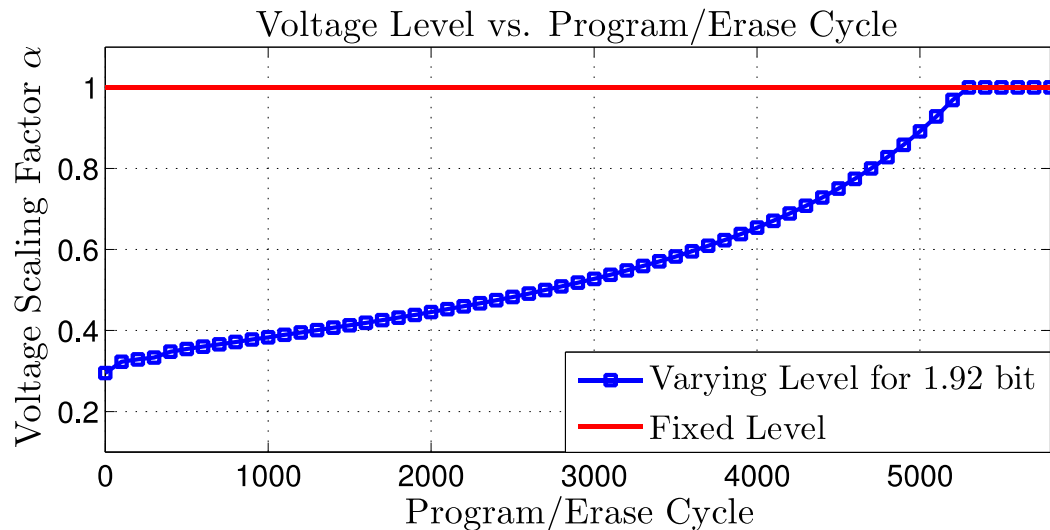
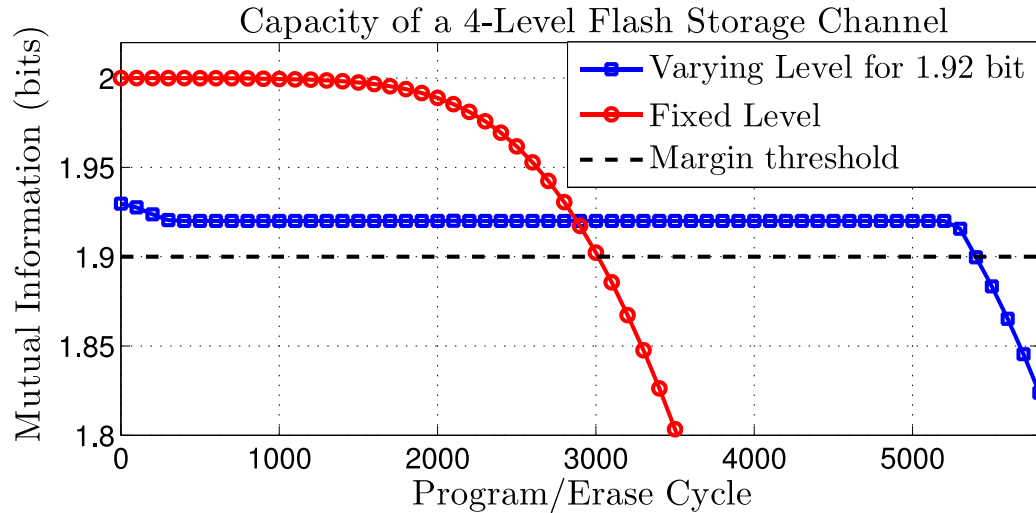
Capacity of a 4-Level Flash Storage Channel



# Setting Voltage Levels to Achieve Needed Capacity

- We can use information theory to **set the code rate** to match the capacity provided by the current channel conditions and the standard voltage levels.
- A much better idea is to **set the voltage levels** to provide the capacity needed to meet the specified storage levels.

# Dynamic Voltage Allocation



# Conclusion

- Channel degradation follows total **number of electrons** pushed through the floating gate rather than the number of P/E cycles.
- Channel can be learned by occasionally using increased precision, which is done anyway to improve decoding
- This can mitigate the mean-shift portion of retention loss.
- Voltage levels can be **dynamically increased** to track the degrading channel.